

SPECIFICATION FOR LCD MODULE

MODULE NO: AFK240320A0-3.5N6NFN REVISION NO: V01

Customer's Approval:						
	SIGNATURE	DATE				
PREPARED BY (RD ENGINEER)						
CHECKED BY						
APPROVED BY						

Records of Revision

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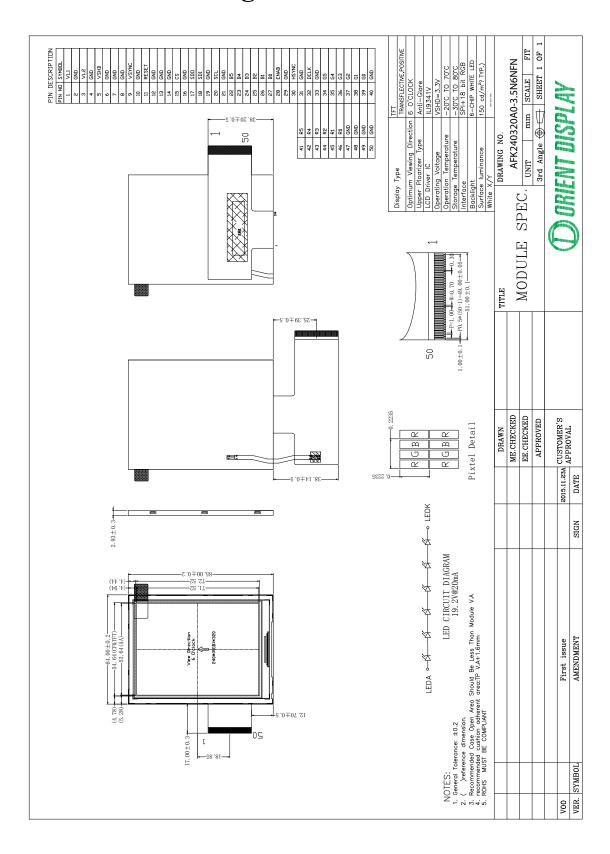
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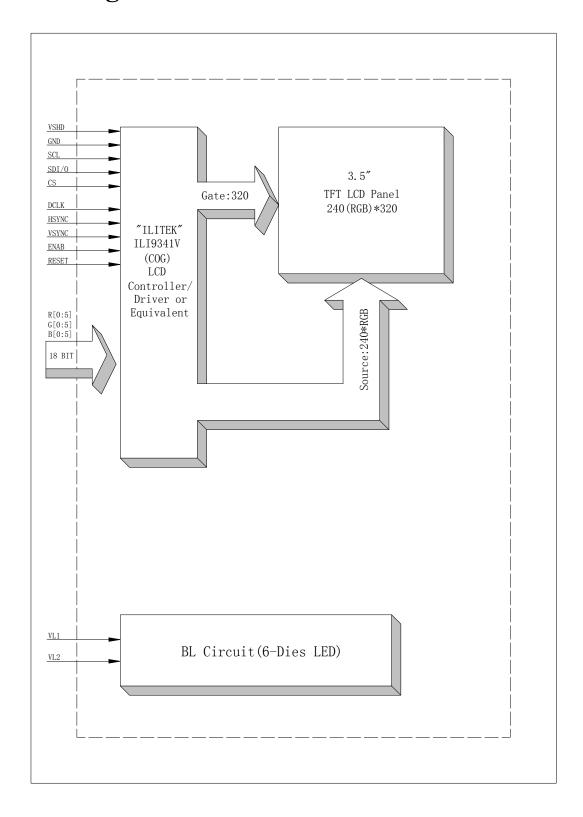
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSFLECTIVE	
MODULE SIZE (W*H*T)	64.00*85.00*2.93	MM
ACTIVE SIZE (W*H)	53.64*71.52	MM
PIXEL PITCH (W*H)	0.2235*0.2235	MM
NUMBER OF DOTS	240*320	
DIVER IC	ILI9341V	
INTERFACE TYPE	SPI+18BIT RGB	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	6	O'CLOCK
GRAY SCALE INVERSION DIRECTION	12	O'CLOCK
COLORS	262K	
BACKLIGHT TYPE	6-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing



3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description			
1	VL1	Anode of LED(High voltage)			
2	GND	Power ground			
3	VL2	Cathode of LED(Low voltage)			
4	GND	Power ground			
5	VSHD	Power supply for digital			
6	GND	Power ground			
7	GND	Power ground			
8	GND	Power ground			
9	VSYNC	Vertical sync. in RGB mode			
10	GND	Power ground			
11	RESET	Reset(Low active)			
12	GND	Power ground			
13	GND	Power ground			
14	GND	Power ground			
15	CS	Chip select input(Low enable)			
16	GND	Power ground			
17	SDO	Serial data output			
18	SDI	Serial data input			
19	GND	Power ground			
20	SCL	Serial interface clock			
21	GND	Power ground			
22~27	B5~B0	Blue data bus			
28	ENAB	Display enable pin from controller			
29	GND	Power ground			
30	HSYNC	Horizontal sync. in RGB mode			
31	GND	Power ground			
32	DCLK	Pixel clock signal in RGB mode			
33	GND	Power ground			
33~38	G5~G0	Green data bus			
40	GND	No connect			
41~46	R5~R0	Red data bus			
47~50	GND	Power ground			

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VSHD	-0.3	4.5	V
Supply voltage for logic	VSHD	-0.3	4.5	V
Supply current (One LED)	I _{LED}		30	mA
Operating temperature	Тор	-20	+70	°C
Storage temperature	T_{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Тур.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VSHD	3.0	3.3	3.6	V	
Supply Voltage for Logic	VSHD	3.0	3.3	3.6	V	
	$V_{\rm IL}$	GND	-	0.3VSHD		
Input Voltage	V _{IH}	0.7 VSHD	-	VSHD	V	
Input leakage Current	I_{LKG}	-1		1	μΑ	

6.2 Backlight Driving Conditions

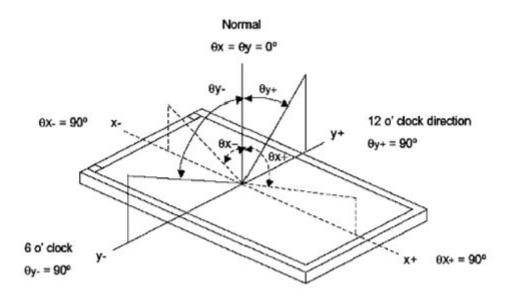
Itom	Symbol	Value			Unit	Remar	
Item	Symbol Min.		Тур.	Max.	Unit	k	
Voltage for LED Backlight	V _F	-	19.2	-	V	$I_L = 20 \text{mA}$	
Current for LED Backlight	IL		20	30	mA		
Power Consumption	P		0.384		W		
LED Life Time		30,000	50,000		Hr	Note	

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25 $^{\circ}$ C

7. Optical Characteristics

ITELEN	ITEM		CONDITIONS	SPEC	IFICAT	ΓΙΟΝS	TINIT	NOTE
I I E IVI		SYMBOL	CONDITIONS	MIN	TYP.	MAX	UNIT	
Luminance		L	I _L =20mA		150		Cd/m ²	
Contrast l	Ratio	CR	θ=0°	100	150			
Pagnanga	Timo	Ton	25℃		35		ma	
Response	Time	Тоғғ	23 C		33		ms	
	Red	XR						
	Reu	YR						
	Green	XG						
CIE Color		YG	Viewing normal					
Coordinate	Blue	Хв	angle					
		YB						
	White	Xw			0.310			
	wnite	Yw			0.320			
	Hor.	$ heta_{\scriptscriptstyle X+}$			45			
Viewing	1101.	$ heta_{\scriptscriptstyle X-}$	CR≥10		40		Degree	Driving backlight
Angle	Ver.	$ heta_{\scriptscriptstyle{Y+}}$	CK>10		40			condition
	V C1.	$ heta_{\scriptscriptstyle Y-}$			55			
Uniformity	Un			80			%	

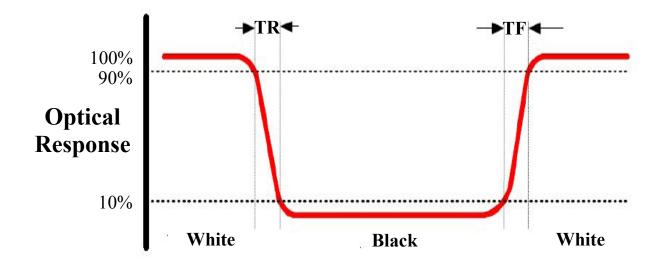
Note 1: Definition of Viewing Angle θx and θy :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance of white state}{Luminance of black state}$$

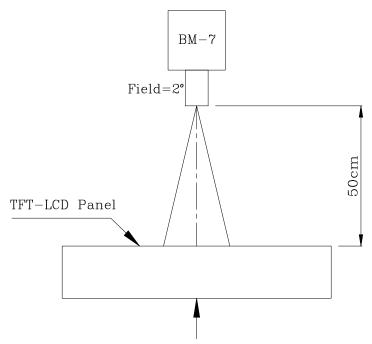
Note 3: Definition of Response Time (Tr,Tf)



Note 4: Definition of Luminance

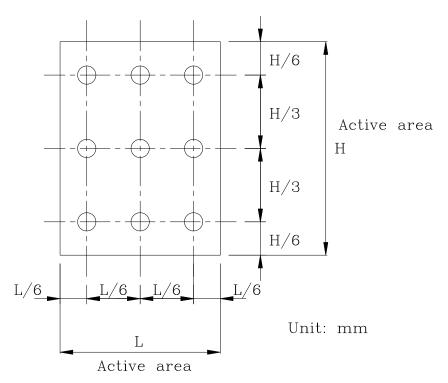
①The Brightness Test Equipment Setup

Field=2° (As measuring "black" image, field=2° is the best testing condition)



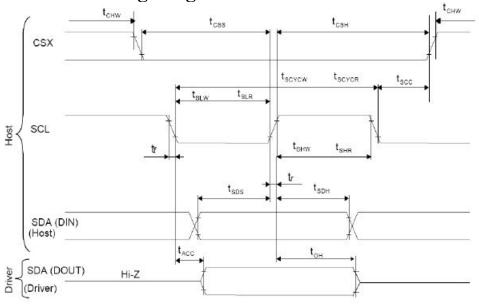
The center of the screen

②The Brightness Test Point Setup



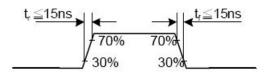
8. Timing Characteristics

8.1 3-WIRES SPI Timing Diagram

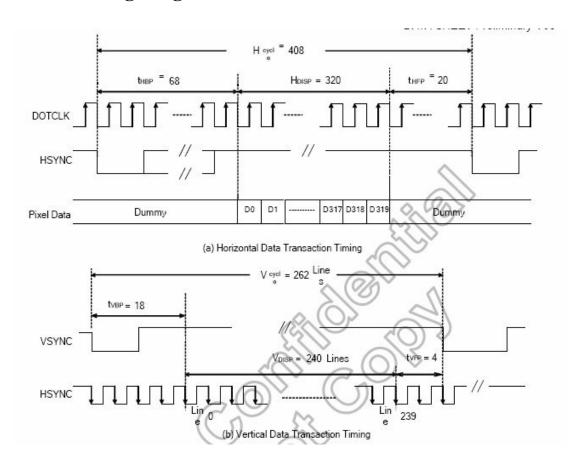


Signal	Symbol	Parameter	min	max	Unit	Description
0000 00	tscycw	Serial Clock Cycle (Write)	100		ns	400
	tshw	SCL "H" Pulse Width (Write)	40		ns	
001	tslw	SCL "L" Pulse Width (Write)	40	2	ns	
SCL	tscycr	Serial Clock Cycle (Read)	150	- 5	ns	
	tshr	SCL "H" Pulse Width (Read)	60		ns	
	tsir	SCL "L" Pulse Width (Read)	60	-	ns	
SDA / SDI	tsds	Data setup time (Write)	30		ns	
(Input)	tsdh	Data hold time (Write)	30	- 2	ns	
SDA/SDO	tacc	Access time (Read)	10	-	ns	
(Output)	toh	Output disable time (Read)	10	50	ns	
CSX	tscc	SCL-CSX	20	- 2	ns	
	tchw	CSX "H" Pulse Width	40		ns	
	tcss	00V 001 T	60		ns	
	tcsh	CSX-SCL Time	65	-	ns	

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V



8.2 RGB Timing Diagram



Characterie	ntine	Symbol	Mi	n.	Ty	p.	Ma	ax.	Unit
Characteristics		Syllibol	24 bit	8 bit	24 bit	8 bit	24 bit	8 bit	Ollit
DOTCLK Frequen	icy_	fDOTCLK	0.70	-	6.5	19.5	10	30	MHz
DOTCLK Period	1	tDOTCLK)	100	33.3	154	51.3	200	7929	ns
Horizontal Freque	ncy (Line)	/\fh\	39	3	14	.9	22	.35	KHz
Vertical Frequenc	y (Refresh)	< fV)	· ·	d	6	0	9	0	Hz
Horizontal Back P	orch	(HBP	-	-50	68	204		5/5%	tDOTCLK
Horizontal Front P	orch	tHFP	0.50	-	20	60		0.50	tDOTCLK
Horizontal Data St	tart Point	tHBP	0.29	21	68	204	120	1929	tDOTCLK
Horizontal Blankin	g Period	tHBP + tHFP	-	20	88	264	190	826	tDOTCLK
Horizontal Display	Area	HDISP	114	49	320	960	720	-	tDOTCLK
Horizontal Cycle		Hcycle			408	1224	450	1350	tDOTCLK
Vertical Back Pord	ch	tVBP	- 18		8	7) 3-		Lines	
Vertical Front Por	ch	tVFP	32	- 4		186	<u>.</u>	Lines	
Vertical Data Star	t Point	tVBP	- 22	33	. 1	8		200	Lines
Vertical Blanking	Period	tVBP + tVFP	() .	d	22		1949		Lines
NTSC		60			240		7		·
Vertical Display Area	PAL	VDISP	8.5		280(PA	LM=0)	-		Lines
	PAL	76			288(PALM=1)		50		
Vertical Cycle	NTSC	Vavala	88	93	26	52	350		*****
Vertical Cycle	PAL	Vcycle	in'		31	13			Lines

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C, 90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30°C for 30 minutes → normal temperature for 5 minutes → +80°C for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ASTM-D-5327.
00	Electrical	Air: $\pm 4KV \ 150 pF/330\Omega \ 5$ times
09 Static Discharge	Contact: ±2KV 150pF/330Ω 5 time	

^{*}Sample size for each test item is 3~5pcs

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

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10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65Minor defect: AQL = 2.5Total defects: AQL = 2.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

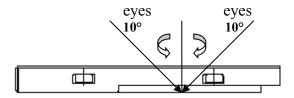
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

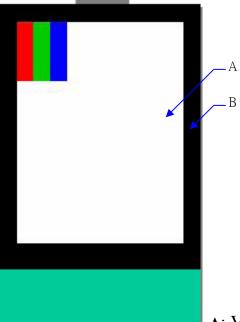
10.5 Standard of the Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5 °C Humidity: 60±10%RH



• Definition of area:



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

- When the standard cannot be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item		Cri	terion		AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 				
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 				2.5
03	LCD and Touch Panel black spots, white spots, contaminati on (non – display)	3.1 Round type: As follows: $\Phi = (X+Y)/2$ $X \leftarrow \qquad $		Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$	Acceptable Q'ty Accept no dense 2 2 1 0 o spots within 3mm.	2.5
		3.2 Line type: (As follows) W Dens	Length(mm) L≤3.0 L≤2.5	mg) Width(mm) $W \le 0.02$ $0.02 < W \le 0.05$ $0.03 < W \le 0.08$ $0.08 < W$	Acceptable Q'ty Accept no dense 2 Rejection to lines within 3mm.	2.5

NO.	Item	Criterion			AQL
	Polarizer	If bubbles are visible, judge using black spot specifications, not easy	Size $Φ$ (mm) Acceptabl Q'ty $Φ \le 0.20 \qquad Accept no dense$		
04	bubbles	to find, must check in	$0.20 < \Phi \le 0.50$	3	2.5
		specify direction	0.50< Φ ≦ 1.00	2	
			1.00< Ф	0	
			Total Q'ty	3	
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass	x: Chip length y: Chip width z: k: Seal width t: Glass thickness the control of	x between panels: $x : Chip len $ $x \le 1/8$	a a ch chip gth a a	2.5

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage $\leq 1/2$ FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\leq 1/2$ alignment area and can not affect the function, we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65

Item	Criterion	AQL		
	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:			
	y: Chip width x: Chip length z: Chip thickness			
	$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$			
Glass crack	Non-conductive portion:	2.5		
	y: Chip width x: Chip length z: Chip thickness			
	$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$			
	 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack 			
	у			
		$ \begin{array}{c} \text{Symbols:} \\ \text{x: Chip length} \text{y: Chip width} \text{z: Chip thickness} \\ \text{k: Seal width} \text{t: Glass thickness} \text{a: LCD side length} \\ \text{L: Electrode pad length} \\ \text{7.2 Protrusion over terminal:} \\ \text{7.2.1 Chip on electrode pad:} \\ \hline \\ y \leq 0.5 \text{mm} \text{x} \leq 1/8 \text{a} 0 < \text{z} \leq \text{t} \\ \hline \\ \text{7.2.2} \\ \text{Non-conductive portion:} \\ \hline \\ \text{Glass crack} \\ \hline \\ y \leq \text{Chip width} \text{x: Chip length} \text{z: Chip thickness}} \\ \hline \\ y \leq \text{Chip width} \text{x: Chip length} \text{thickness}} \\ \hline \\ y \leq \text{L} \text{x} \leq 1/8 \text{a} 0 < \text{z} \leq \text{t} \\ \hline \\ \hline \\ \hline \\ \text{O: If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.} \\ \hline \\ \hline \\ \text{O: If the product will be heat sealed by the customer, the alignment mark must must mot be damaged.} \\ \hline \\ \hline \end{array}$		

NO.	Item	Criterion A				
14	Touch Panel Chipped glass	k: Seal width t: 'L: Electrode pad length 14.1 General glass of 14.1.1 Chip on panel z: Chip thickness Z≦t O Unit: mm	hip: I surface and crack between the surface and crack between th	x: Chip length x ≤ 1/8a		
		z: Chip thickness	y: Chip width	x: Chip length		
		z≦t	≤ 1/2 k and not over viewing area	x ≤ 1/8a		
		⊙ Unit: mm⊙ If there are 2 or m	nore chips, x is the total	length of each chip		

NO.	Item	Criterion		
15	Touch Panel(Fish eye、dent and bubble on film)	$\begin{array}{ c c c }\hline SIZE(mm) & Acceptable Q'ty\\ \hline \Phi \leq 0.2 & Accept no dense\\ \hline 0.2 < D \leq 0.4 & 5\\ \hline 0.4 < D \leq 0.5 & 2\\ \hline 0.5 < D & 0\\ \hline \end{array}$	2.5	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion ($\leq 2.5\%$), it is acceptable.	2.5	
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5	
18	LCD Ripple	Touch the touch panel, cannot see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5	
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65	

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10°C and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

----TBD